



# SPP2323

## Dual P-Channel Enhancement Mode MOSFET

### DESCRIPTION

The SPP2323 is the Dual P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications notebook computer power management and other battery powered circuits where high-side switching, low in-line power loss, and resistance to transients are needed.

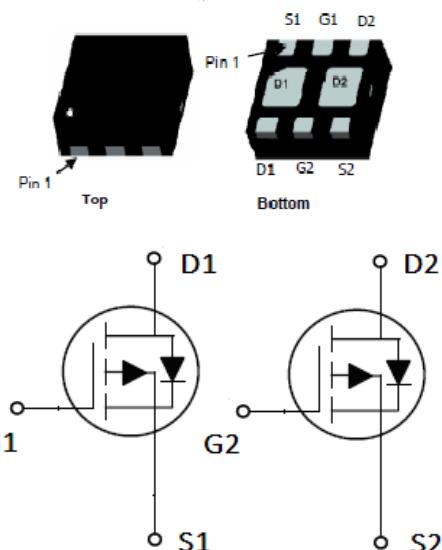
### FEATURES

- -20V/-3.3A,RDS(ON)=65mΩ@ VGS=-4.5V
- -20V/-2.8A,RDS(ON)=85mΩ@VGS=-2.5V
- -20V/-2.3A,RDS(ON)=130mΩ@VGS=-1.8V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- TDFN2x2-6L package design

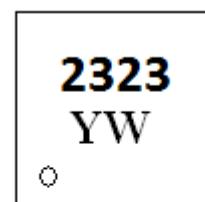
### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

### PIN CONFIGURATION(TDFN2x2-6L)



### PART MARKING



Y : Year Code  
W: Week Code



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### PIN DESCRIPTION

Pin	Symbol	Description
1	S1	Source 1
2	G1	Gate 1
3	D2	Drain 2
4	S2	Source 2
5	G2	Gate 2
6	D1	Drain1
Exposed Backside Metal	D1/D2	Drain

### ORDERING INFORMATION

Part Number	Package	Part Marking
SPP2323TDN6RGB	TDFN2x2-6L	2323YW

※ Week Code : A ~ Z( 1 ~ 26 ) ; a ~ z( 27 ~ 52 )

※ SPP2323TDN6RGB : Tape Reel ; Pb – Free ; Halogen -Free

### ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-20	V
Gate –Source Voltage	V <sub>GSS</sub>	±10	V
Continuous Drain Current(T <sub>J</sub> =150°C)	T <sub>A</sub> =25°C	I <sub>D</sub>	A
	T <sub>A</sub> =100°C		
Pulsed Drain Current	I <sub>DM</sub>	-16	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.6	A
Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	W
	T <sub>A</sub> =70°C		
Operating Junction Temperature	T <sub>J</sub>	-55/150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	T≤ 5sec	R <sub>θJA</sub>	°C/W
	Steady State		
		65	
		95	



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### ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, ID=-250uA	-20			
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>D</sub> =V <sub>GS</sub> , ID=-250uA	-0.3		-1.0	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>D</sub> =0V, V <sub>GS</sub> =±10V			-10	uA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>D</sub> =-20V, V <sub>GS</sub> =0V			-1	
		V <sub>D</sub> =-16V, V <sub>GS</sub> =0V T <sub>J</sub> =125°C			-10	uA
On-State Drain Current	I <sub>D(on)</sub>	V <sub>D</sub> ≤ -4.5V, V <sub>GS</sub> =-5V	-10			A
Drain-Source On-Resistance	R <sub>D(on)</sub>	V <sub>GS</sub> =-4.5V, ID=-3.3A		45	65	
		V <sub>GS</sub> =-2.5V, ID=-2.8A		60	85	
		V <sub>GS</sub> =-1.8V, ID=-2.3A		90	130	
		V <sub>GS</sub> =-1.5V, ID=-1A		100	140	
Forward Transconductance	g <sub>fs</sub>	V <sub>D</sub> =-10V, ID=-1A		2.2		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V			-1	V
<b>Dynamic</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>D</sub> =-10V, V <sub>GS</sub> =-0V, F=1MHz		515	745	
Output Capacitance	C <sub>oss</sub>			55	80	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			20	30	
Total Gate Charge	Q <sub>g</sub>	V <sub>D</sub> =-10V, V <sub>GS</sub> =-4.5V, ID=-3A		6.4		
Gate-Source Charge	Q <sub>gs</sub>			0.9		nC
Gate-Drain Charge	Q <sub>gd</sub>			1.6		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-10V, ID=-1A V <sub>GEN</sub> =-4.5V, R <sub>G</sub> =25Ω		5		
	t <sub>r</sub>			17.4		
Turn-Off Time	t <sub>d(off)</sub>			40.7		
	t <sub>f</sub>			11.4		nS



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### TYPICAL CHARACTERISTICS

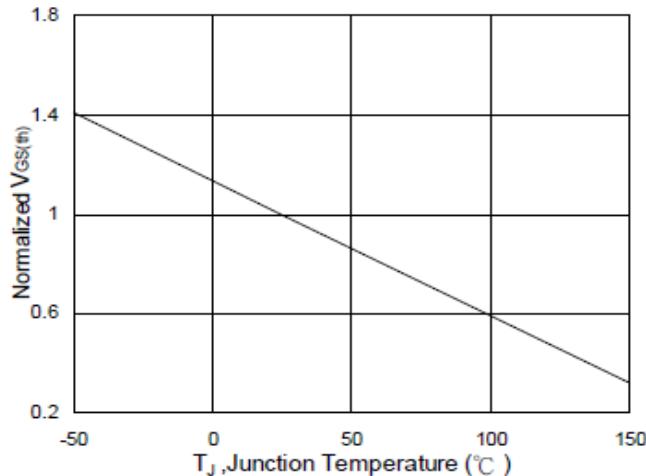


Fig. 1 Normalized  $V_{GS(th)}$  vs. Temp

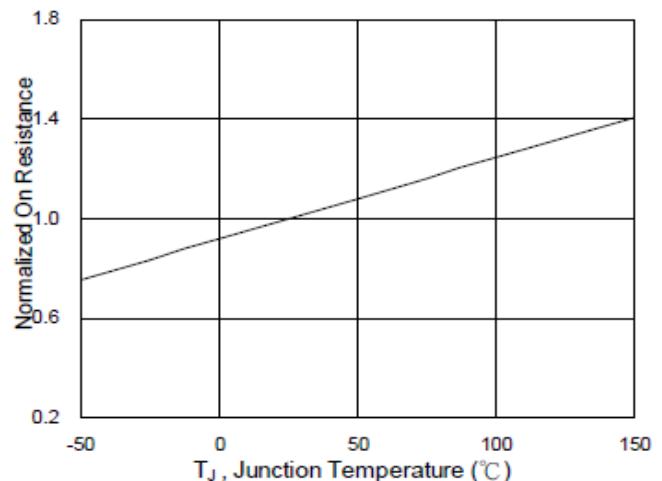


Fig. 2 Normalized On-Resistance vs. Temp

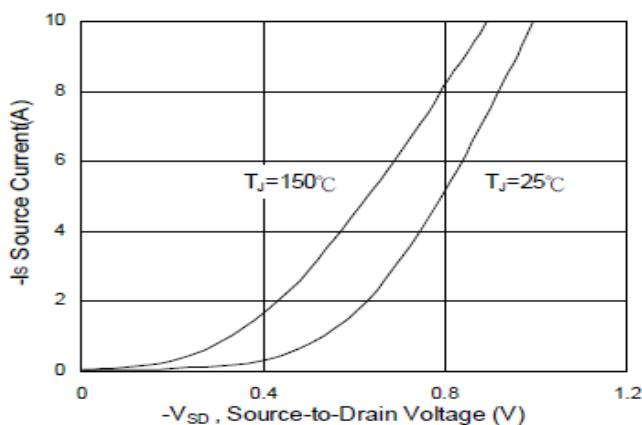


Fig. 3 Output Characteristics

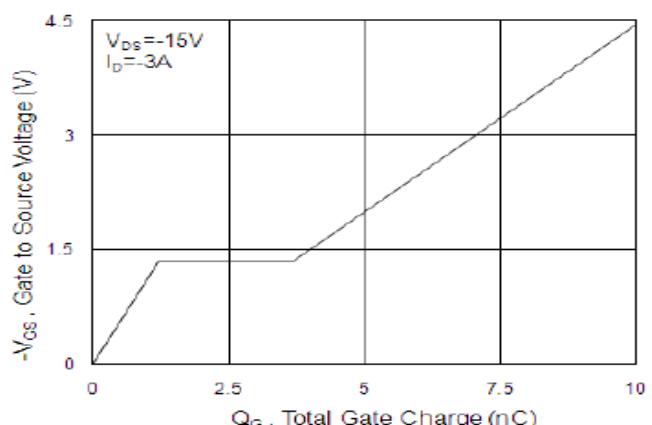


Fig. 4 Gate Charge Characteristics

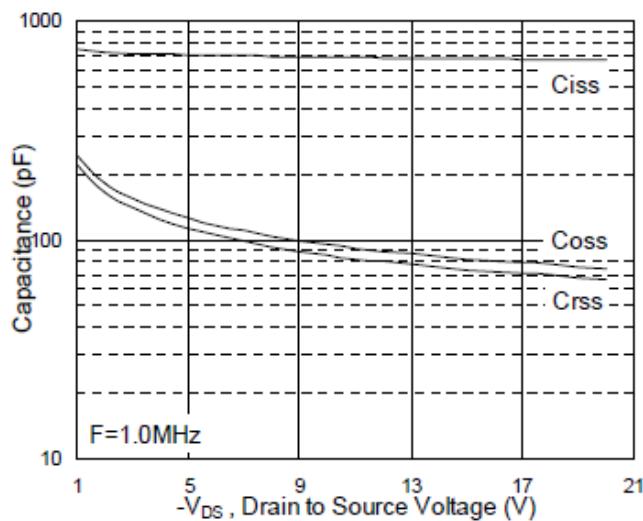


Fig 5 Capacitance vs. Drain Voltage

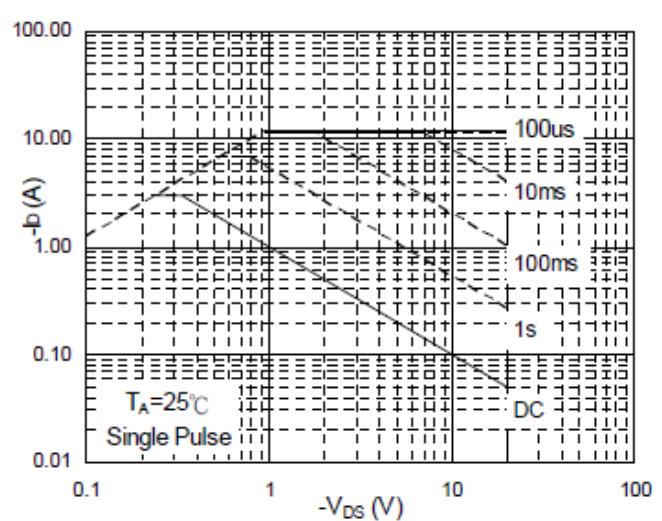


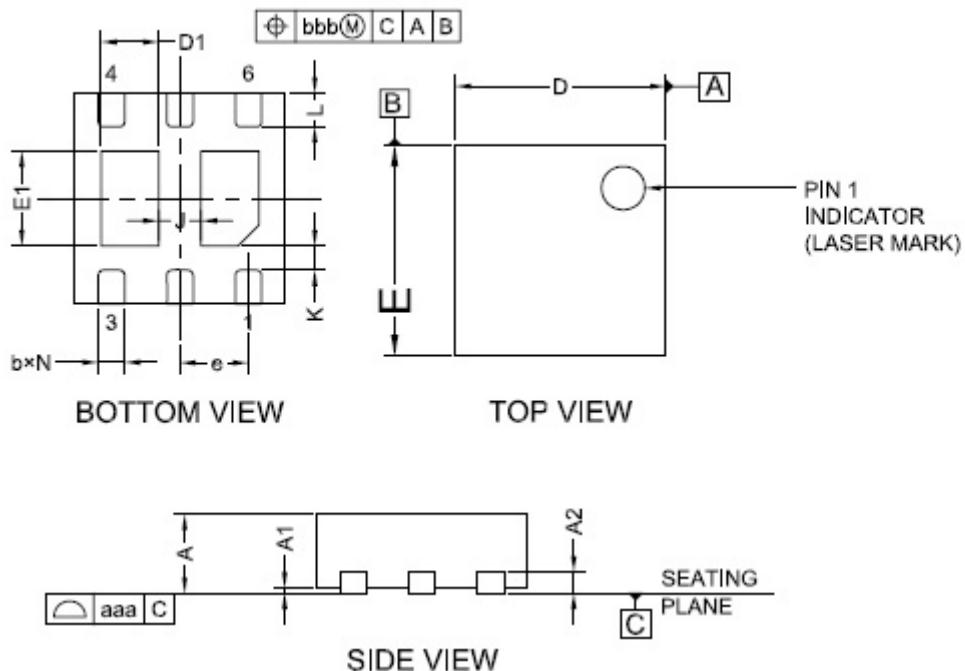
Fig. 6 Safe Operation Area



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### TDFN2x2-6L PACKAGE OUTLINE



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e		0.65BSC	
L	0.27	0.32	0.37
J		0.40BSC	
K		0.20MIN	
N		6	
aaa		0,08	
bbb		0.10	



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